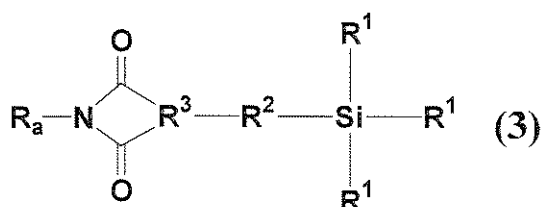
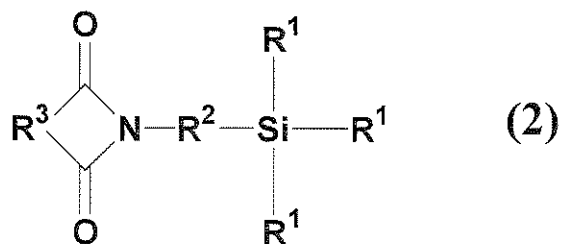
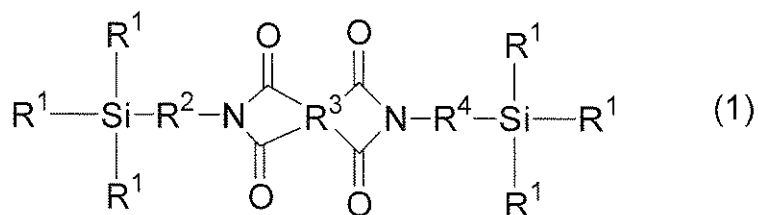


ABSTRACT

It is intended to provide a photosensitive siloxane composition comprising (a) polysiloxane, (b) a quinone diazide compound, (c) a solvent and (d) one or more kinds of imidosilane compounds represented by the general formulas (1) to (3):



which makes it possible to provide a cured film having low shrinkage during curing and high transparency after thermal curing, suppressing the occurrence of cracks after dipping in an alkaline solvent and exhibiting excellent adhesiveness to a substrate, wherein R¹s may be the same or different and each represents an alkyl group having 1 to 6 carbon atoms, an alkoxy group having 1 to 6 carbon atoms, a phenyl group, a phenoxy group or an organic group replaced with them, R² and R⁴ represent each

a divalent organic group having 1 to 10 carbon atoms, R^3 represents an organic group not containing a silicon atom and having 2 to 20 carbon atoms (provided that R^3 represents an organic group other than a phenyl group in the general formula (1) and represents an organic group not containing an unsaturated bond other than an alicyclic group in the general formula (2)), and R_a represents a hydrogen atom or an organic group not containing a silicon atom and having 1 to 20 carbon atoms.